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13. A semiconductor chip-mounting board according to claim 1,

wherein the strengthening land formed on the semiconductor chip-mounting face is strip-shaped extending radially to the mounted semiconductor chip in a length preventing the bonding material from spreading beyond a width thereof over the semiconductor chip-mounting face, and in a direction from a contact point thereof to a bump on the electrode to a central part of the semiconductor chip; and

wherein a sealing resin is provided between the semiconductor chip and the semiconductor chip-mounting board, and the semiconductor chip-mounting board has a glass transition point exceeding a setting temperature of the sealing resin so as to reduce differences of thermal expansion coefficients at a setting of the bonding material and the sealing resin, resulting in reduction of stresses acting to bonded parts between the lands and bumps on the electrodes.

14. A semiconductor chip-mounting board according to claim 1,

wherein a strengthening land is provided at the semiconductor chip-mounting face, the strengthening land being connected via a bonding material to a non-operating electrode formed on the circuit formation face and

functionally not related to the semiconductor chip, thereby to increase a connection strength between the semiconductor chip and the semiconductor chip-mounting board;

wherein the strengthening land formed on the semiconductor chip-mounting face is strip-shaped extending radially to the mounted semiconductor chip in a length preventing the bonding material from spreading beyond a width thereof over the semiconductor chip-mounting face, and in a direction from a contact point thereof to a bump on the electrode to a central part of the semiconductor chip; and

wherein the semiconductor chip-mounting board has a glass transition point exceeding a drying and a setting temperature of the bonding material.

15. A semiconductor chip-mounting board according to claim 1,

wherein the semiconductor chip-mounting board contains a material having a thermal expansion coefficient not smaller than that of silicon; and

wherein the semiconductor chip-mounting board has a glass transition point exceeding a drying and a setting temperature of the bonding material.

16. A semiconductor chip-mounting board according to claim 1,

wherein the semiconductor chip-mounting board contains a material having a thermal expansion coefficient

not smaller than that of silicon; and

wherein a sealing resin is provided between the semiconductor chip and the semiconductor chip-mounting board, and the semiconductor chip-mounting board has a glass transition point exceeding a setting temperature of the sealing resin.